



Call for Papers



The 7th VLSI PACKAGING WORKSHOP of JAPAN

Nov. 30 - Dec. 2, 2004

Kyoto, Japan

Sponsored by the IEEE CPMT Society and National Institute for Standards and Technology

The VLSI Packaging Workshop of Japan has been held every other year since 1992 in the best season of Kyoto, the ancient capital of Japan, and it has become a well-known international workshop for advanced packaging technologies. The committee strongly encourages you to attend this workshop and participate in the discussion, in order to understand technology trends and find the proper target for technology development. Bring your latest research results and share with the participants who are experts from industry and the grove of Academe, and discuss with them. Anybody contributing to human progress through electronics is very welcome at this workshop. The following areas of technology are primarily of interest to the participants:

- + Advanced Fine Pitch Packaging
- + 3D Packaging & COC (Chip on Chip)
- + Micro Bumping Technology
- + Laminated Materials & Processing
- + RF Components & Modules
- + Integrated Passives
- + Packaging for Optoelectronics
- + Failure Mechanisms & Reliability Improvement
- + Electrical Performance & Thermal Management
- + Wafer Level CSP
- + Manufacturing Technology
- + Pb Free Interconnections
- + Materials for High Speed Application & Wafer Process
- + RFID tags
- + System in Package (SIP)
- + MEMS Packaging Technologies
- + Assembly and Packaging Challenges for Cu/Low-k Chips
- + Wafer Level Burn-in

The official language of this workshop is English. 30 minutes is allocated for each presentation, and it should include 5 - 10 minutes for Q&A. Authors who give outstanding papers will receive official recommendations for paper submission to the IEEE Transactions by the Japan Chapter and the Workshop Committee. This workshop will be held at Kyoto Research Park where the 6th Workshop was held in 2002.

Submission of abstracts:

Those who wish to contribute to the workshop should send a two-page summary of their paper (including figures) to the Program Chair **by May 28th, 2004**. The title of the paper as well as the names and affiliations of all authors must appear on the summary. If the paper is accepted, the summary shall be written to fit in a four-page format for the workshop's Proceedings **by September 3rd, 2004**. Notification of acceptance will be given **by July 9th, 2004**.

Program Chair:

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